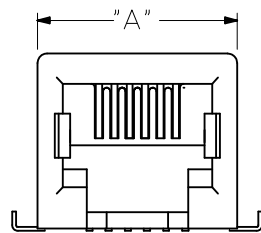
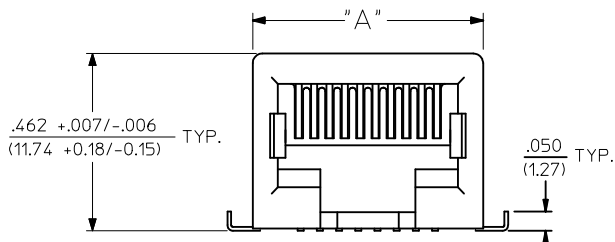


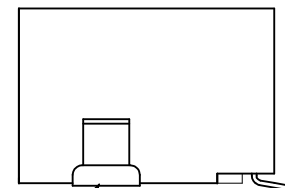
HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B
6	6	.520 (13.21)	.250 (6.35)
6	4	.520 (13.21)	.150 (3.81)
6	2	.520 (13.21)	.050 (1.27)
8	8	.600 (15.24)	.350 (8.89)
8	6	.600 (15.24)	.250 (6.35)



6 CIRCUIT ASSEMBLY



8 CIRCUIT ASSEMBLY



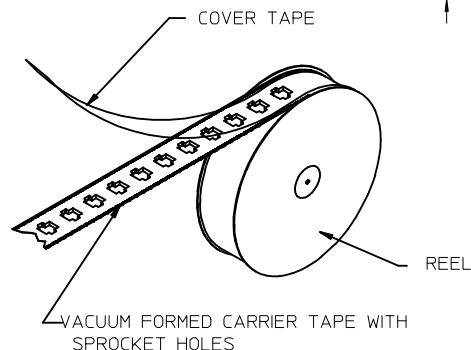
FITTING NAILS
SEE NOTE 5

TERMINAL TAILS
SEE NOTE 5

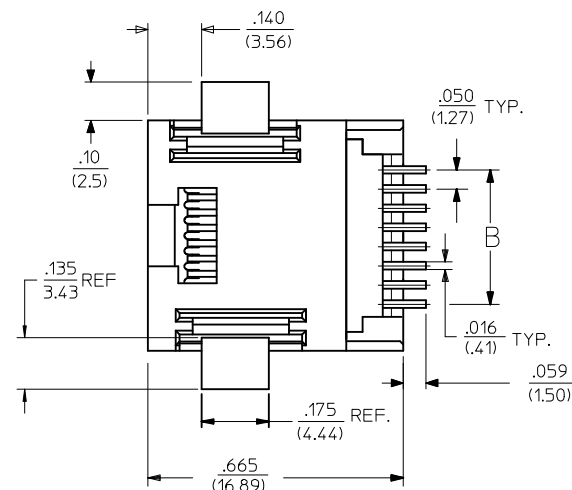
ASSEMBLY ITEM NO.	CONNECTOR SIZE	CIRCUIT SIZE	TERMINAL PLATING	TAPE & REEL PACKAGING No.	VOIDED CIRCUITS
43743-6001	6	6	A	PK-70873-7001	NA
43743-6002	6	6	B		
43743-6003	6	6	C		
43743-6101	6	4	A		
43743-6102	6	4	B		
43743-6103	6	4	C	PK-70873-7001	
43743-8101	8	8	A	PK-70873-7002	
43743-8102	8	8	B		
43743-8103	8	8	C		
43743-8201	8	6	A		
43743-8202	8	6	B		
43743-8203	8	6	C		
43743-8301	8	4	A		
43743-8302	8	4	B		
43743-8303	8	4	C	PK-70873-7002	
43743-6201	6	2	A	PK-70873-7001	
43743-6202	6	2	B	PK-70873-7001	
43743-6203	6	2	C	PK-70873-7001	NA

NOTES:

- MATERIAL:
HOUSING & INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
FITTING NAILS: BRASS, .010/(0.25) THICK
- FINISH:
TERMINALS:
A = SELECT GOLD IN CONTACT AREA: .000050/(0.00127) MIN.,
*SELECT MATTE TIN IN PC TAIL AREA: .000100/(0.00254) MN.,
WITH OVERALL NICKEL UNDERPLATE: .000050/(0.00127) MIN.
B = SELECT GOLD IN CONTACT AREA: .000030/(0.00076) MIN.,
*SELECT MATTE TIN IN PC TAIL AREA: .000100/(0.00254) MN.,
WITH OVERALL NICKEL UNDERPLATE: .000050/(0.00127) MIN.
C = SELECT GOLD IN CONTACT AREA: .000015/(0.00038) MIN.,
*SELECT MATTE TIN IN PC TAIL AREA: .000100/(0.00254) MN.,
WITH OVERALL NICKEL UNDERPLATE: .000050/(0.00127) MIN.
FITTING NAILS:
*100 MICROINCHES MATTE TIN OVER 50 MICROINCHES NICKEL UNDERPLATE
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR FITTING NAILS.
- PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43743-0001.
- PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES TO BE PACKAGED USING TAPE & REEL SYSTEM.
- COPLANARITY SPECIFICATION:
WHEN AN ASSEMBLY IS PLACED UPON A LEVEL SURFACE, THE MAXIMUM GAP BETWEEN THE LEVEL SURFACE AND ALL TERMINAL TAILS AND BOTH FITTING NAILS IS .006/(0.15).
- FOR ASSEMBLIES HAVING VOIDED CIRCUITS, THE TAIL PORTION IS CUT AND REMOVED. THE MATING PORTION OF THE TERMINAL REMAINS INTACT. VOIDED CIRCUITS MUST BE THE SAME FOR BOTH PARTS.
- CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

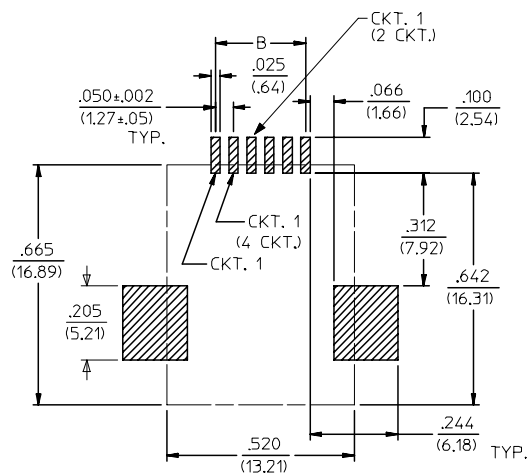


TAPE AND REEL PACKAGING

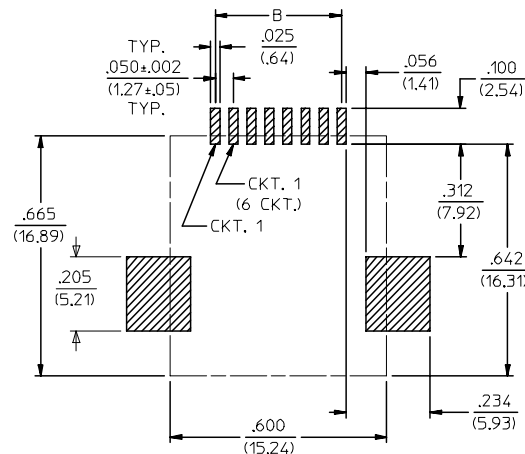


2	H
1	J3
SHT	REV

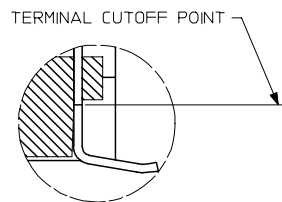
REVISED NOTES EC NO: UCP2009-1244 DRWN:JKLOSTER/ER 2008/12/10 CHKD:JBELL 2008/12/10 APPR:FSM/TH 2008/12/10 J3	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 1:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION 		
			mm	INCH	DRAWN BY PEARSON	DATE 6/18/96	TITLE SURFACE MOUNT MODULAR JACK				
			4 PLACES ± --- ± ---	CHECKED BY PEARSON	DATE 6/18/96						
			3 PLACES ± --- ± .010	APPROVED BY EDGLEY	DATE 6/18/96	MOLEX INCORPORATED SDA-43743-****					
			2 PLACES ± 0.25 ± .014	MATERIAL NO. SEE CHARTS	DOCUMENT NO. SDA-43743-****						SHEET NO. 1 OF 2
1 PLACE ± 0.36 ± ---	ANGULAR ± 1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



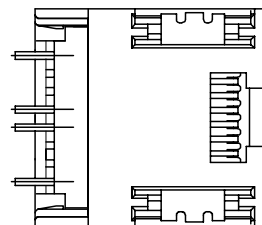
PC BOARD LAYOUT FOR
6 POSITION HOUSING
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR
8 POSITION HOUSING
(COMPONENT SIDE OF BOARD)



VIEW SHOWING TYPICAL TERMINAL
CUTOFF OF TAIL (SEE NOTE 5) FOR VOIDED CIRCUITS.



TYPICAL VIEW SHOWING VOIDED CIRCUIT
(CIRCUITS 2,3,6 & 7 SHOWN VOIDED)

SEE SHEET ONE EC NO: UCP2004-0798 DRAWN:LSCHMDT 2004/01/05 CHKD:LSCHMDT 2004/01/05 APPR:FSMITH 2004/01/08	QUALITY SYMBOLS ▽ = 0 ▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± .014 1 PLACE ± 0.36 ± --- ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SCALE --- INCH DIMENSION STYLE IN/MM DRAWN BY DATE PEARSON 06/18/96 CHECKED BY DATE PEARSON 06/18/96 APPROVED BY DATE EDGLEY 06/18/96	DESIGN UNITS INCH THIRD ANGLE PROJECTION REVISE ON CAD ONLY	TITLE SURFACE MOUNT MODULAR JACK MOLEX INCORPORATED SEE TABLE SDA-43743-**** THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	SHEET NO. 2 OF 2

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9